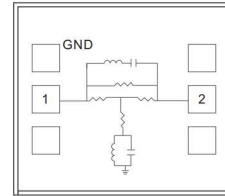


Performance

- Frequency: 8~12GHz
- Insertion Loss: ≤ 0.7 dB
- Attenuation: 2dB
- Impedance: 50 Ω
- Chip size: 0.80*0.75*0.1 mm

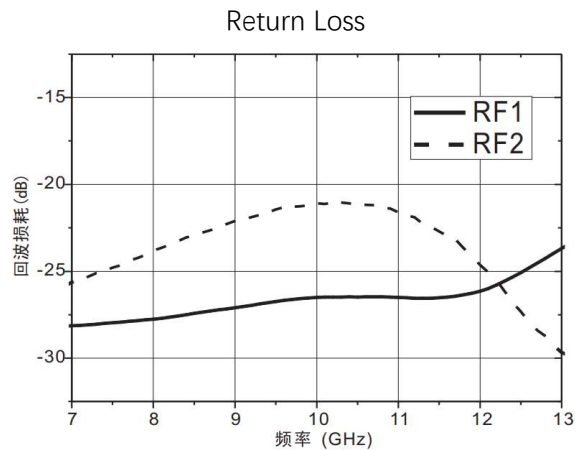
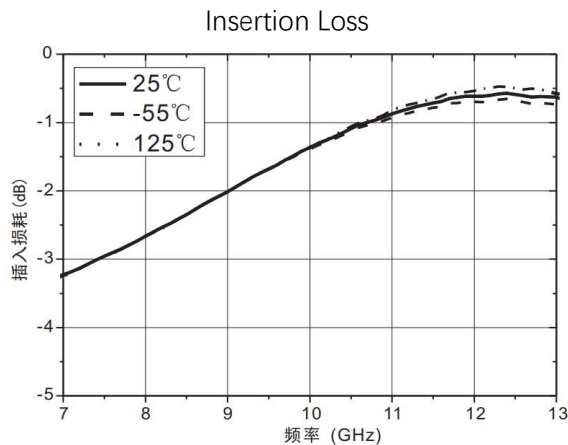
Function Diagram



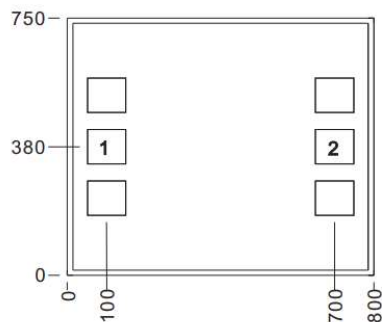
Electrical Specifications (TA=+25°C, 50 Ω system)

Parameter	Min	Typical	Max	Unit
Frequency Range		8~12		GHz
Insertion Loss	-	0.7	0.8	dB
Attenuation	-	2.0	2.1	dB
Input Return Loss	20	21	-	dB
Output Return Loss	24	25	-	dB

Test Curves (Die chip test)



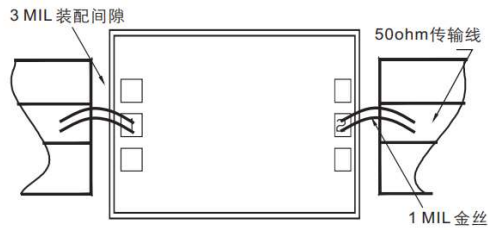
Outline Size



Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads are gold plated
Pads size: 100*100 μm
5. Don't bond on thru holes
6. Tolerance: $\pm 50\mu\text{m}$

Assembly Drawing



Bonding Pads Definition

Number	Symbol	Description
RF1、RF2	RF Ports	RF ports, 50 ohm impedance
	GND	Bottom side of chip must be grounded

Absolute Max. Ratings

Static Protection Grade	Class 1A
Input Power	27 dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS